

ABSTRACT OF THE DISCLOSURE

COMPLIANT SUBSTRATE
IN PARTICULAR FOR HETERO-EPITAXIAL DEPOSITING

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The invention relates to a compliant substrate (5) comprising a carrier (1) and at least one thin layer (4), formed on the surface of the carrier and intended to receive, in integral manner, a stress-giving structure. The carrier (1) and the thin layer (4) are joined to one another by joining means (3) such that the stresses brought by said structure are absorbed in whole or in part by the thin layer (4) and/or by the joining means (3) which comprise at least one joining zone chosen from among the following joining zones: a layer of microcavities and/or a bonding interface whose bonding energy is controlled to permit absorption of said stresses.

15 Figure 1C